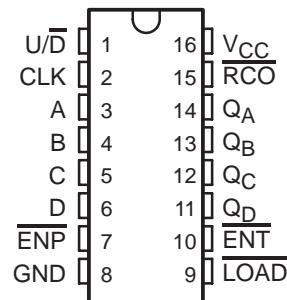


- Fully Synchronous Operation for Counting and Programming
- Internal Look-Ahead Circuitry for Fast Counting
- Carry Output for N-Bit Cascading
- Fully Independent Clock Circuit
- Package Options Include Plastic Small-Outline Packages and Standard Plastic 300-mil DIPs

D OR N PACKAGE
(TOP VIEW)



description

This synchronous, presettable, 4-bit up/down binary counter features an internal carry look-ahead circuitry for cascading in high-speed counting applications. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when so instructed by the count-enable ($\overline{\text{ENP}}$, $\overline{\text{ENT}}$) inputs and internal gating. This mode of operation eliminates the output counting spikes that are normally associated with asynchronous (ripple-clock) counters. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of the clock waveform.

This counter is fully programmable; that is, it may be preset to any number between 0 and its maximum count. The load-input circuitry allows loading with the carry-enable output of cascaded counters. As loading is synchronous, setting up a low level at the load (LOAD) input disables the counter and causes the outputs to agree with the data inputs after the next clock pulse.

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous application without additional gating. Instrumental in accomplishing this function are two count-enable ($\overline{\text{ENP}}$, $\overline{\text{ENT}}$) inputs and a ripple-carry ($\overline{\text{RCO}}$) output. Both $\overline{\text{ENP}}$ and $\overline{\text{ENT}}$ must be low to count. The direction of the count is determined by the level of the up/down ($\overline{\text{U/D}}$) input. When $\overline{\text{U/D}}$ is high, the counter counts up; when low, it counts down. Input $\overline{\text{ENT}}$ is fed forward to enable the $\overline{\text{RCO}}$. $\overline{\text{RCO}}$ thus enabled will produce a low-level pulse while the count is zero (all inputs low) counting down or maximum (9 or 15) counting up. This low-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at $\overline{\text{ENP}}$ or $\overline{\text{ENT}}$ are allowed regardless of the level of the clock input. All inputs are diode clamped to minimize transmission-line effects, thereby simplifying system design.

The SN74F169 features a fully independent clock circuit. Changes at control inputs ($\overline{\text{ENP}}$, $\overline{\text{ENT}}$, LOAD or $\overline{\text{U/D}}$) that will modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) will be dictated solely by the conditions meeting the setup and hold times.

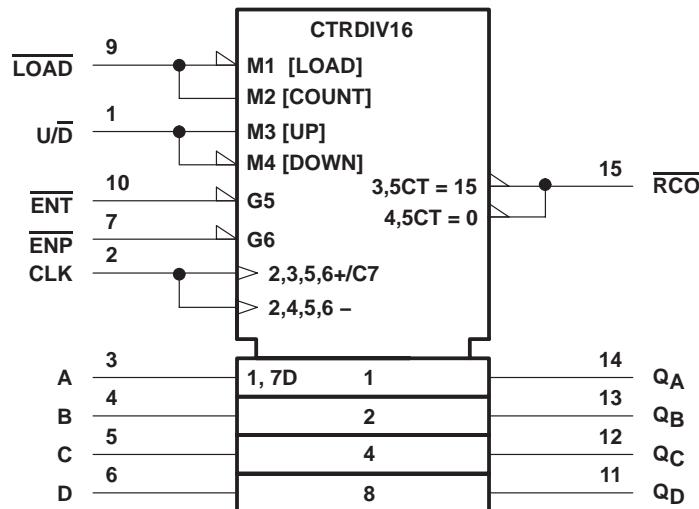
The SN74F169 is characterized for operation from 0°C to 70°C.

SN74F169

SYNCHRONOUS 4-BIT UP/DOWN BINARY COUNTER

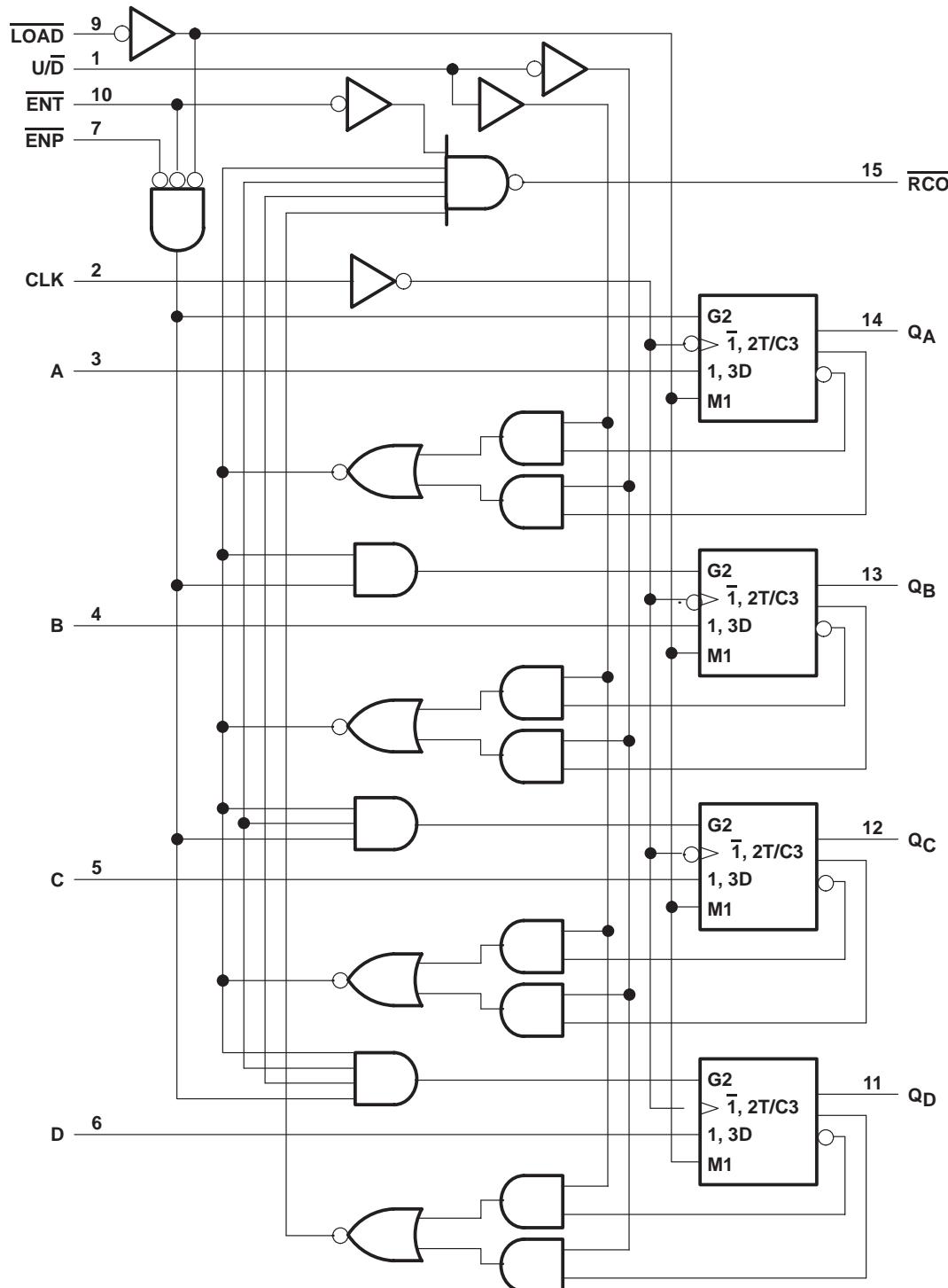
SDFS089 – MARCH 1987 – REVISED OCTOBER 1993

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)

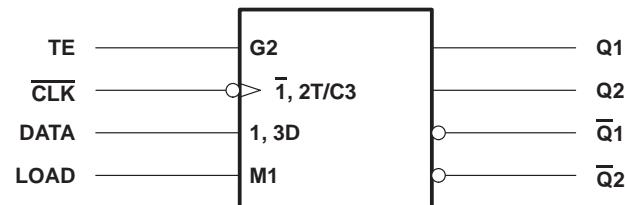


SN74F169

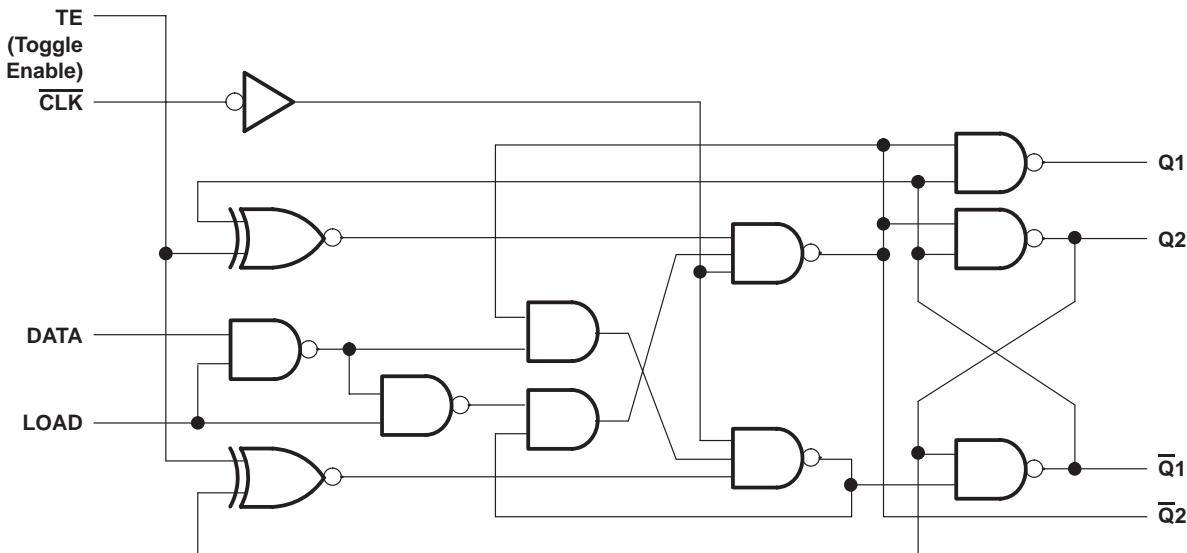
SYNCHRONOUS 4-BIT UP/DOWN BINARY COUNTER

SDFS089 – MARCH 1987 – REVISED OCTOBER 1993

logic symbol, each flip-flop



logic diagram, each flip-flop (positive logic)



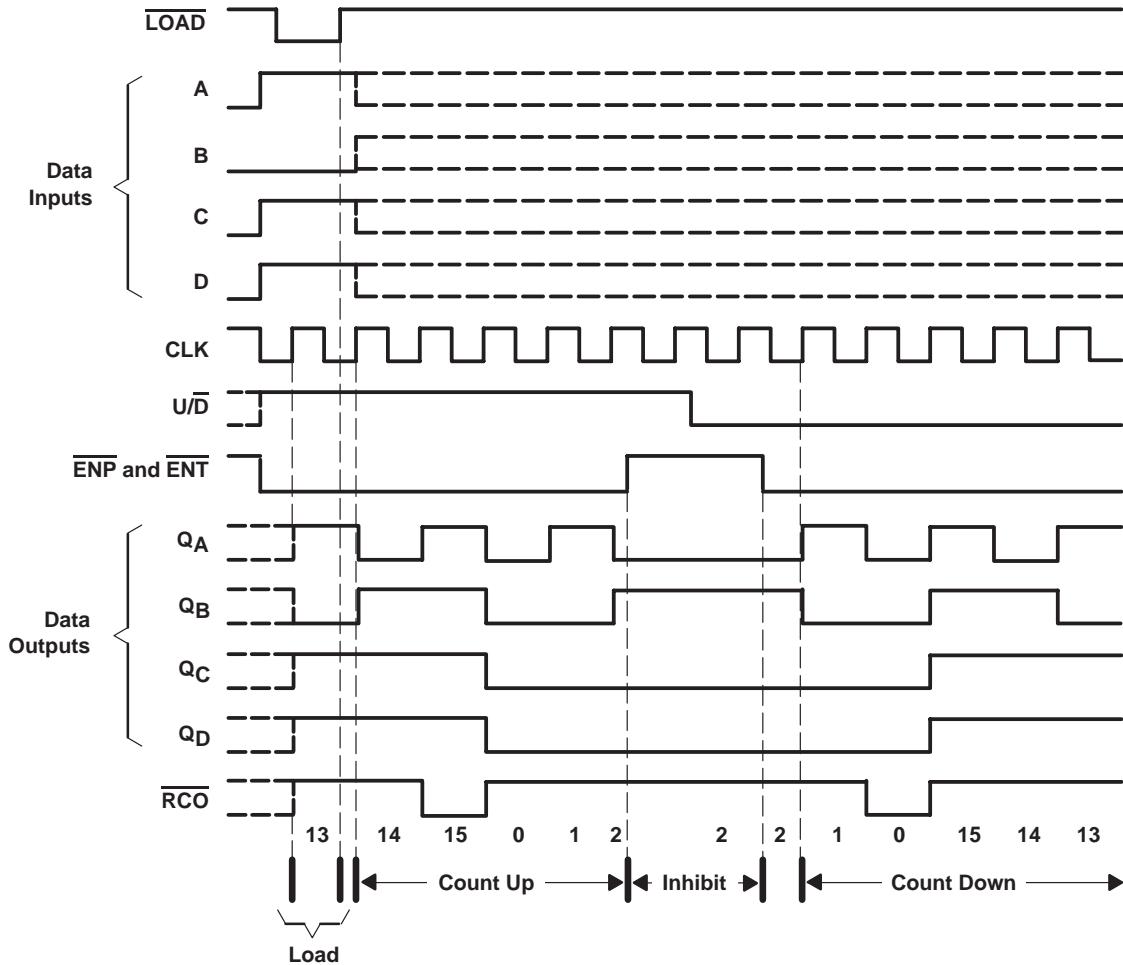
FUNCTION TABLE
(each flip-flop)

COUNTER INPUTS		FLIP-FLOP INPUTS				OUTPUTS	
LOAD	CLK	LOAD	TE	CLK	DATA	Q	Q̄
L	↑	H	L	↓	H	H	L
L	↑	H	L	↓	L	L	H
H	↑	L	H	↓	X	Q ₀	Q ₀
H	↑	L	L	↓	X	Q ₀	Q̄ ₀

typical load, count, and inhibit sequences

Illustrated below is the following sequence:

1. Load (preset) to binary thirteen
2. Count up to fourteen, fifteen (maximum), zero, one, and two
3. Inhibit
4. Count down to one, zero (minimum), fifteen, fourteen, and thirteen



SN74F169

SYNCHRONOUS 4-BIT UP/DOWN BINARY COUNTER

SDF089 – MARCH 1987 – REVISED OCTOBER 1993

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–1.2 V to 7 V
Input current range	–30 mA to 5 mA
Voltage range applied to any output in the high state	–0.5 V to V_{CC}
Current into any output in the low state	40 mA
Operating free-air temperature range	0°C to 70°C
Storage temperature range	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input voltage ratings may be exceeded provided the input current ratings are observed.

recommended operating conditions

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
I_{IK}	Input clamp current			–18	mA
I_{OH}	High-level output current			–1	mA
I_{OL}	Low-level output current			20	mA
T_A	Operating free-air temperature	0	70		°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 4.5$ V, $I_I = –18$ mA			–1.2	V
V_{OH}	$V_{CC} = 4.5$ V, $I_{OH} = –1$ mA	2.5	3.4		V
	$V_{CC} = 4.75$ V, $I_{OH} = –1$ mA	2.7			
V_{OL}	$V_{CC} = 4.5$ V, $I_{OL} = 20$ mA	0.3	0.5		V
I_I	$V_{CC} = 5.5$ V, $V_I = 7$ V		0.1		mA
I_{IH}	$V_{CC} = 5.5$ V, $V_I = 2.7$ V			20	μA
I_{IL}	$V_{CC} = 5.5$ V, $V_I = 0.5$ V			–1.2	mA
				–0.6	
$I_{OS}^§$	$V_{CC} = 5.5$ V, $V_O = 0$	–60	–150		mA
I_{CC}	$V_{CC} = 5.5$ V, See Note 2		38	52	mA

[†] All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

[‡] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: I_{CC} is measured after applying a momentary 4.5 V, then ground, to the clock input with B and ENT inputs high and all other inputs low.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251-1443

SN74F169
SYNCHRONOUS 4-BIT UP/DOWN BINARY COUNTER

SDFS089 – MARCH 1987 – REVISED OCTOBER 1993

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

			$V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$		MIN	MAX	UNIT
			MIN	MAX			
f_{clock}	Clock frequency		0	100	0	90	MHz
t_w	Pulse duration	CLK high or low	5	5.5			ns
t_{su}	Setup time	Data before \overline{CLK}^\uparrow	High or low	4	4.5		ns
		\overline{LOAD} before \overline{CLK}^\uparrow	High or low	8	9		
		\overline{ENP} and \overline{ENT} before \overline{CLK}^\uparrow	High or low	5	6		
		U/\overline{D} before \overline{CLK}^\uparrow	High	11	12.5		
		U/\overline{D} before \overline{CLK}^\uparrow	Low	7	8		
t_h	Hold time	Data after \overline{CLK}^\uparrow	High or low	3	3.5		ns
		\overline{LOAD} after \overline{CLK}^\uparrow	High or low	0	0		
		\overline{ENP} and \overline{ENT} after \overline{CLK}^\uparrow	High or low	0	0		
		U/\overline{D} after \overline{CLK}^\uparrow	High or low	0	0		

switching characteristics (see Note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5 \text{ V}$, $C_L = 50 \text{ pF}$, $R_L = 500 \Omega$, $T_A = 25^\circ\text{C}$			$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$, $C_L = 50 \text{ pF}$, $R_L = 500 \Omega$, $T_A = \text{MIN to MAX}^\dagger$		UNIT
			MIN	TYP	MAX	MIN	MAX	
f_{max}			100	115		90		MHz
t_{PLH}	CLK	Q	2.2	6.1	8.5	2.2	9.5	ns
t_{PHL}			3.2	8.6	11.5	3.2	13	
t_{PLH}	CLK	\overline{RCO}	4.7	11.6	15.5	4.7	17	ns
t_{PHL}			3.2	8.1	11	3.2	12.5	
t_{PLH}	\overline{ENT}	\overline{RCO}	1.7	4.1	6	1.7	7	ns
t_{PHL}			1.7	5.6	8	1.7	9	
t_{PLH}	U/\overline{D}	\overline{RCO}	2.7	8.1	11	2.7	12.5	ns
t_{PHL}			3.2	7.6	10.5	3.2	12	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 3: Load circuits and waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74F169D	NRND	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F169	
SN74F169N	NRND	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74F169N	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.



www.ti.com

PACKAGE OPTION ADDENDUM

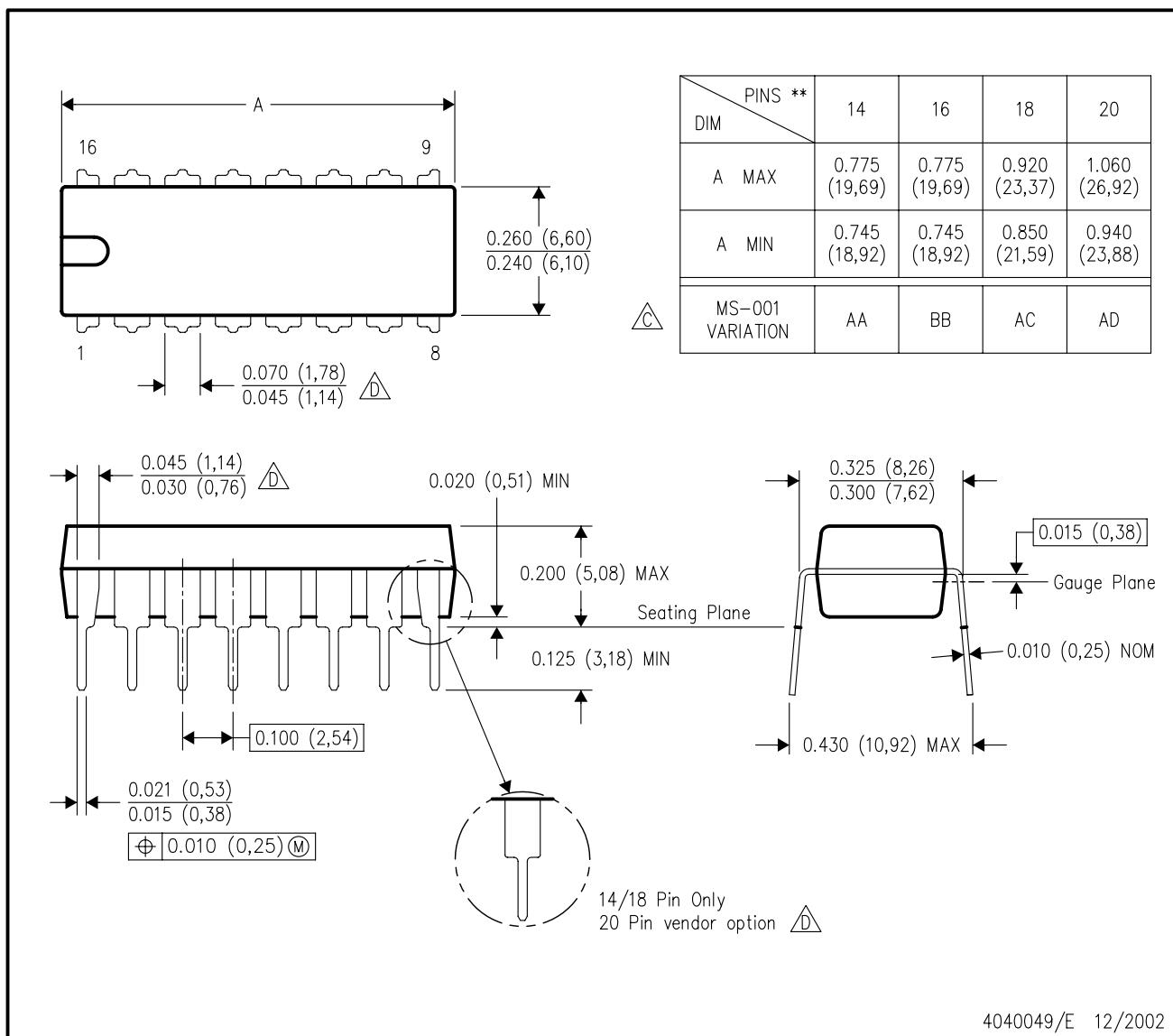
10-Jun-2014

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

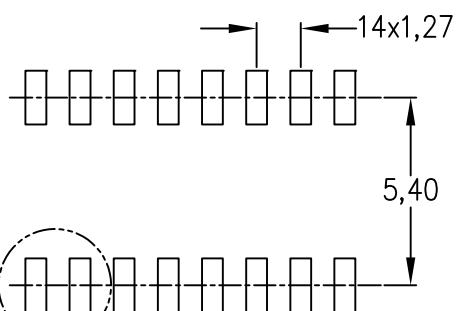
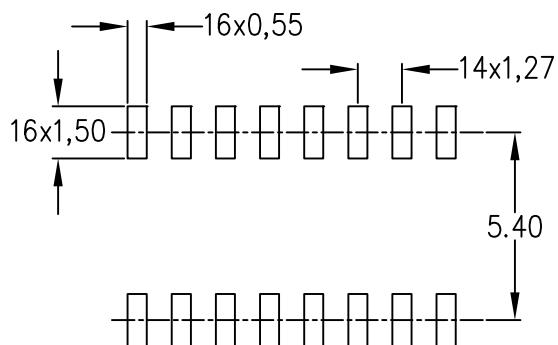
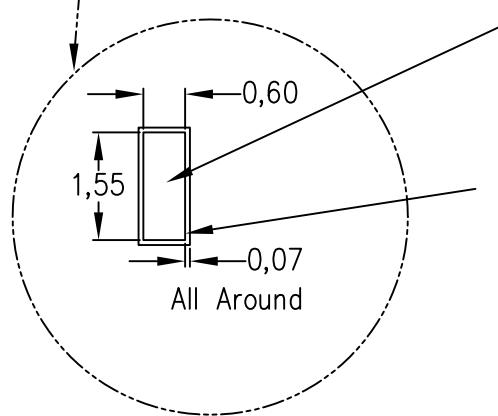
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.

D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.

E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)Stencil Openings
(Note D)Example
Non Soldermask Defined PadExample
Pad Geometry
(See Note C)Example
Solder Mask Opening
(See Note E)

4211283-4/E 08/12

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Publication IPC-7351 is recommended for alternate designs.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products	Applications
Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity
	TI E2E Community
	e2e.ti.com